## Dual 64-Bit Static Shift Register

The MC14517B dual 64-bit static shift register consists of two identical, independent, 64-bit registers. Each register has separate clock and write enable inputs, as well as outputs at bits 16, 32, 48, and 64. Data at the data input is entered by clocking, regardless of the state of the write enable input. An output is disabled (open circuited) when the write enable input is high. During this time, data appearing at the data input as well as the 16-bit, 32-bit, and 48-bit taps may be entered into the device by application of a clock pulse. This feature permits the register to be loaded with 64 bits in 16 clock periods, and also permits bus logic to be used. This device is useful in time delay circuits, temporary memory storage circuits, and other serial shift register applications.

#### Features

- Diode Protection on All Inputs
- Fully Static Operation
- Output Transitions Occur on the Rising Edge of the Clock Pulse
- Exceedingly Slow Input Transition Rates May Be Applied to the Clock Input
- 3-State Output at 64th-Bit Allows Use in Bus Logic Applications
- Shift Registers of any Length may be Fully Loaded with 16 Clock Pulses
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low–Power TTL Loads or One Low–Power Schottky TTL Load Over the Rated Temperature Range
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable
- This Device is Pb-Free and is RoHS Compliant

#### MAXIMUM RATINGS (Voltages Referenced to V<sub>SS</sub>)

	00,		
Parameter	Symbol	Value	Unit
DC Supply Voltage Range	V <sub>DD</sub>	-0.5 to +18.0	V
Input or Output Voltage Range (DC or Transient)	V <sub>in</sub> , V <sub>out</sub>	–0.5 to V <sub>DD</sub> + 0.5	V
Input or Output Current (DC or Transient) per Pin	I <sub>in</sub> , I <sub>out</sub>	±10	mA
Power Dissipation per Package (Note 1)	PD	500	mW
Operating Temperature Range	T <sub>A</sub>	-55 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-65 to +150	°C
Lead Temperature (8–Second Soldering)	TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Temperature Derating: Plastic "D/DW" Package: -7.0 mW/°C From 65°C to 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.



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SOIC-16 WB DW SUFFIX CASE 751G

#### MARKING DIAGRAM



#### **PIN ASSIGNMENT**

Q16 <sub>A</sub> [	1●	16 🛛 V <sub>DD</sub>
Q48 <sub>A</sub> [	2	15 ] Q16 <sub>B</sub>
WE <sub>A</sub> [	3	14 🛛 Q48 <sub>B</sub>
C <sub>A</sub> [	4	13 🛛 WE <sub>B</sub>
Q64 <sub>A</sub> [	5	12 ] C <sub>B</sub>
Q32 <sub>A</sub> [	6	11 🛛 Q64 <sub>B</sub>
D <sub>A</sub> [	7	10 🛛 Q32 <sub>B</sub>
v <sub>ss</sub> [	8	9] D <sub>B</sub>

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MC14517BDWG	SOIC-16 WB (Pb-Free)	47 Units/Rail
MC14517BDWR2G	SOIC-16 WB (Pb-Free)	1000 / Tape & Reel
NLV14517BDWR2G	SOIC-16 WB (Pb-Free)	1000 / Tape & Reel

<sup>+</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Cleak	Write Enable	Data	46 Dit Ton	22 Bit Ten	49 Dit Top	C4 Dit Ton
Clock	LIIADIe	Data	16–Bit Tap	32–Bit Tap	48–Bit Tap	64–Bit Tap
0	0	Х	Content of 16–Bit Displayed	Content of 32–Bit Displayed	Content of 48–Bit Displayed	Content of 64–Bit Displayed
0	1	Х	High Impedance	High Impedance	High Impedance	High Impedance
1	0	х	Content of 16–Bit Displayed	Content of 32–Bit Displayed	Content of 48–Bit Displayed	Content of 64–Bit Displayed
1	1	Х	High Impedance	High Impedance	High Impedance	High Impedance
٦	0	Data entered into 1st Bit	Content of 16–Bit Displayed	Content of 32–Bit Displayed	Content of 48–Bit Displayed	Content of 64–Bit Displayed
_	1	Data entered into 1st Bit	Data at tap entered into 17–Bit	Data at tap entered into 33–Bit	Data at tap entered into 49–Bit	High Impedance
~	0	Х	Content of 16–Bit Displayed	Content of 32–Bit Displayed	Content of 48–Bit Displayed	Content of 64–Bit Displayed
$\sim$	1	Х	High Impedance	High Impedance	High Impedance	High Impedance

#### FUNCTIONAL TRUTH TABLE (X = Don't Care)

#### ELECTRICAL CHARACTERISTICS (Voltages Referenced to V<sub>SS</sub>)

			- 5	5°C		25°C		125°C		
Characteristic	Symbol	V <sub>DD</sub> Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
Output Voltage "0" Level V <sub>in</sub> = V <sub>DD</sub> or 0	V <sub>OL</sub>	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
"1" Level $V_{in} = 0$ or $V_{DD}$	V <sub>OH</sub>	5.0 10 15	4.95 9.95 14.95		4.95 9.95 14.95	5.0 10 15		4.95 9.95 14.95	- - -	Vdc
Input Voltage "0" Level $(V_O = 4.5 \text{ or } 0.5 \text{ Vdc})$ $(V_O = 9.0 \text{ or } 1.0 \text{ Vdc})$ $(V_O = 13.5 \text{ or } 1.5 \text{ Vdc})$	V <sub>IL</sub>	5.0 10 15	_ _ _	1.5 3.0 4.0	_ _ _	2.25 4.50 6.75	1.5 3.0 4.0	_ _ _	1.5 3.0 4.0	Vdc
"1" Level ( $V_O = 0.5 \text{ or } 4.5 \text{ Vdc}$ ) ( $V_O = 1.0 \text{ or } 9.0 \text{ Vdc}$ ) ( $V_O = 1.5 \text{ or } 13.5 \text{ Vdc}$ )	V <sub>IH</sub>	5.0 10 15	3.5 7.0 11		3.5 7.0 11	2.75 5.50 8.25		3.5 7.0 11		Vdc
$\begin{array}{l} \mbox{Output Drive Current} \\ (V_{OH} = 2.5 \ Vdc) \\ (V_{OH} = 4.6 \ Vdc) \\ (V_{OH} = 9.5 \ Vdc) \\ (V_{OH} = 13.5 \ Vdc) \end{array}$	I <sub>OH</sub>	5.0 5.0 10 15	-3.0 -0.64 -1.6 -4.2	- - -	-2.4 -0.51 -1.3 -3.4	-4.2 -0.88 -2.25 -8.8	- - -	-1.7 -0.36 -0.9 -2.4	- - -	mAdc
	I <sub>OL</sub>	5.0 10 15	0.64 1.6 4.2		0.51 1.3 3.4	0.88 2.25 8.8		0.36 0.9 2.4	- - -	mAdc
Input Current	l <sub>in</sub>	15	-	±0.1	-	±0.00001	±0.1	-	±1.0	μAdc
Input Capacitance (V <sub>in</sub> = 0)	C <sub>in</sub>	-	-	-	-	5.0	7.5	-	-	pF
Quiescent Current (Per Package)	I <sub>DD</sub>	5.0 10 15		5.0 10 20		0.005 0.010 0.015	5.0 10 20		150 300 600	μAdc
Total Supply Current (Note 3, 4) (Dynamic plus Quiescent, Per Package) (C <sub>L</sub> = 50 pF on all outputs, all buffers switching)	Ι <sub>Τ</sub>	5.0 10 15			$I_{T} = (8)$	4.2 μΑ/kHz) f 3.8 μΑ/kHz) f 3.7 μΑ/kHz)	+ I <sub>DD</sub>	·	·	μAdc
Three–State Leakage Current	I <sub>TL</sub>	15	-	±0.1	_	±0.0001	±0.1	_	±3.0	μAdc

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
2. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
3. The formulas given are for the typical characteristics only at 25°C.
4. To calculate total supply current at loads other than 50 pF: I<sub>T</sub>(C<sub>L</sub>) = I<sub>T</sub>(50 pF) + (C<sub>L</sub> - 50) Vfk where: I<sub>T</sub> is in µA (per package), C<sub>L</sub> in pF, V = (V<sub>DD</sub> - V<sub>SS</sub>) in volts, f in kHz is input frequency, and k = 0.004.

#### MC14517B

#### SWITCHING CHARACTERISTICS (Note 5) ( $C_L = 50 \text{ pF}, T_A = 25^{\circ}C$ )

Characteristic	Symbol	V <sub>DD</sub>	Min	Typ (Note 6)	Max	Unit
Output Rise and Fall Time $t_{TLH}$ , $t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{TLH}$ , $t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ $t_{TLH}$ , $t_{THL} = (0.65 \text{ ns/pF}) C_L + 9.5 \text{ ns}$	t <sub>TLH</sub> , t <sub>THL</sub>	5.0 10 15	- - -	100 50 40	200 100 80	ns
Propagation Delay Time $t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 390 \text{ ns}$ $t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 177 \text{ ns}$ $t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 115 \text{ ns}$	t <sub>PLH</sub> , t <sub>PHL</sub>	5.0 10 15	_ _ _	475 210 140	770 300 215	ns
Clock Pulse Width	t <sub>WH</sub>	5.0 10 15	330 125 100	170 75 60		ns
Clock Pulse Frequency	f <sub>cl</sub>	5.0 10 15	- - -	3.0 6.7 8.3	1.5 4.0 5.3	MHz
Clock Pulse Rise and Fall Time	t <sub>TLH</sub> , t <sub>THL</sub>	5.0 10 15	See (Note 7)			-
Data to Clock Setup Time	t <sub>su</sub>	5.0 10 15	0 10 15	- 40 - 15 0	- - -	ns
Data to Clock Hold Time	t <sub>h</sub>	5.0 10 15	150 75 35	75 25 10		ns
Write Enable to Clock Setup Time	t <sub>su</sub>	5.0 10 15	400 200 110	170 65 50		ns
Write Enable to Clock Release Time	t <sub>rel</sub>	5.0 10 15	380 180 100	160 55 40		ns

 The formulas given are for the typical characteristics only at 25°C.
 Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 When shift register sections are cascaded, the maximum rise and fall time of the clock input should be equal to or less than the rise and fall time of the data outputs, driving data inputs, plus the propagation delay of the output driving stage.







#### MC14517B



Figure 4. AC Test Waveforms



#### **MECHANICAL CASE OUTLINE** PACKAGE DIMENSIONS

#### SOIC-16 WB CASE 751G ISSUE E SCALE 1:1 NOTES A DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 1. CONTROLLING DIMENSION: MILLIMETERS 2. 16 🗢 0.25@ B@ В DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. з. <u>A A A A</u> RRRR ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS. 4. MAXIMUM MOLD PROTRUSION OR FLASH TO BE 0.15 PER SIDE. 5. MILLIMETERS DIM MIN. MAX. H Н Α 2.35 2.65 h 8 45 0.25 A1 0.10 -16X B e DETAIL A в 0.35 0.49 0.2500 TAS BS END VIEW С 0.23 0.32 TOP VIEW D 10.15 10.45 7.40 7.60 Ε 1.27 BSC e 16X н 10.05 10.55 -L h 0.53 REF SEATIN **A1** 0.50 0.90 L SIDE VIEW М 0\* 7\* DETAIL A 2X SCALE 0000|0000 GENERIC 11.00 **MARKING DIAGRAM\*** 1 16X 1.62 .27 XXXXXXXXXXXX PITCH XXXXXXXXXXXX RECOMMENDED AWLYYWWG MOUNTING FOOTPRINT H H Η 1 H Н XXXXX = Specific Device Code = Assembly Location А = Wafer Lot WL YY = Year ww = Work Week G = Pb-Free Package \*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may

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